



US00D731448S

(12) **United States Design Patent**
Kinoshita et al.

(10) **Patent No.:** **US D731,448 S**
(45) **Date of Patent:** **** Jun. 9, 2015**

(54) **POLISHING PAD FOR SUBSTRATE
POLISHING APPARATUS**

FOREIGN PATENT DOCUMENTS

(71) Applicant: **EBARA CORPORATION**, Tokyo (JP)

JP 1334824 S 5/2008
TW 1396602 B1 5/2013

(72) Inventors: **Masaki Kinoshita**, Tokyo (JP);
Toshifumi Kimba, Tokyo (JP)

* cited by examiner

(73) Assignee: **EBARA CORPORATION**, Tokyo (JP)

Primary Examiner — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Pearne & Gordon LLP

(**) Term: **14 Years**

(57) **CLAIM**

(21) Appl. No.: **29/489,180**

The ornamental design for a polishing pad for substrate polishing apparatus, as shown and described.

(22) Filed: **Apr. 28, 2014**

DESCRIPTION

(30) **Foreign Application Priority Data**

Oct. 29, 2013 (JP) 2013-025148
Oct. 29, 2013 (JP) 2013-025149

FIG. 1 is a top plan view of a first embodiment of a polishing pad for substrate polishing apparatus, showing our new design;
FIG. 2 is a bottom plan view thereof;

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

FIG. 3 is a front view thereof, the rear view being identical;
FIG. 4 is a right side view thereof, the left side view being identical;

(58) **Field of Classification Search**
USPC D13/182; 257/E21.001, E21.002,
257/E21.21, E21.23; 361/230, 233, 234;
451/64, 65, 66, 67, 72, 259, 278, 285,
451/286, 287, 288, 290
See application file for complete search history.

FIG. 5 is an enlarged, top plan view thereof, taken along lines 5-5 of FIG. 1;

FIG. 6 is an enlarged, cross-sectional view thereof, taken along lines 6-6 of FIG. 5;

(56) **References Cited**

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FIG. 7 is a top plan view of a second embodiment of a polishing pad for substrate polishing apparatus, showing our new design;

FIG. 8 is a bottom plan view thereof;

FIG. 9 is a front view thereof, the rear view being identical;

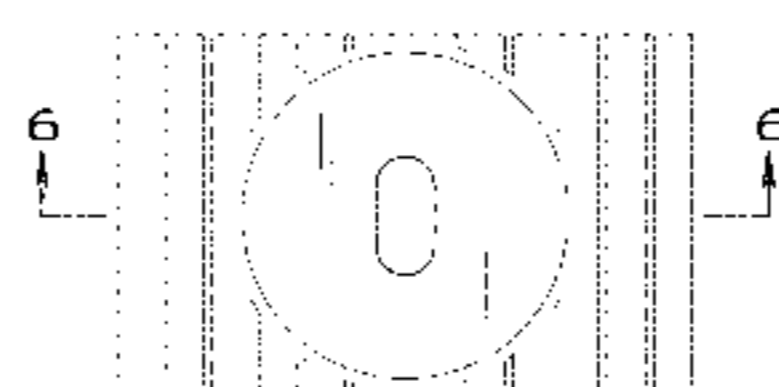
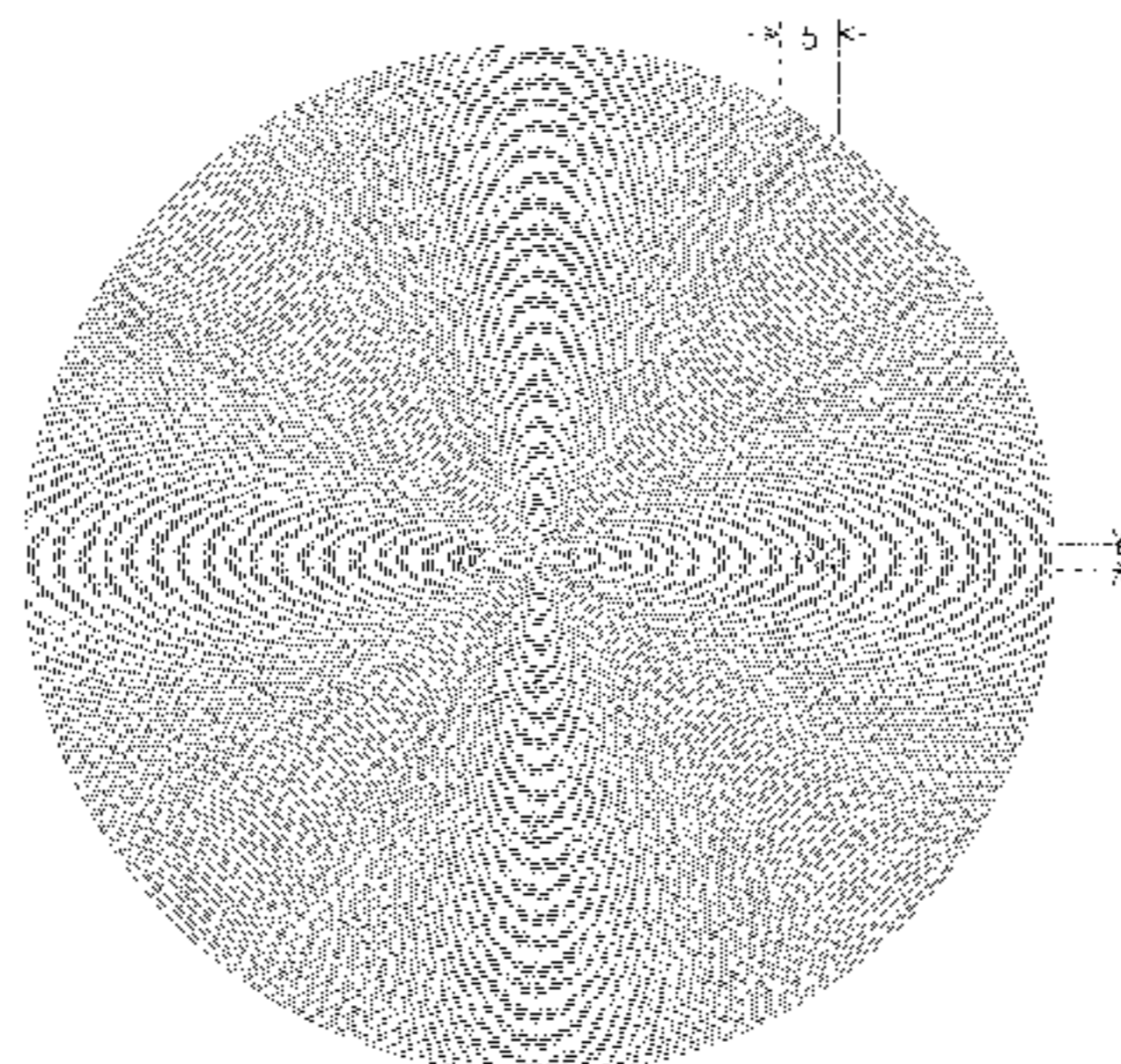
FIG. 10 is a right side view thereof, the left view being identical;

FIG. 11 is an enlarged, partial top plan view thereof, taken along lines 11-11 of FIG. 7; and,

FIG. 12 is an enlarged, cross-sectional view thereof, taken along lines 12-12 of FIG. 11.

The dashed-dot-dashed lines represent the boundary lines of the claimed design. The even dashed broken lines depict environment subject matter only and form no part of the claimed design.

1 Claim, 9 Drawing Sheets



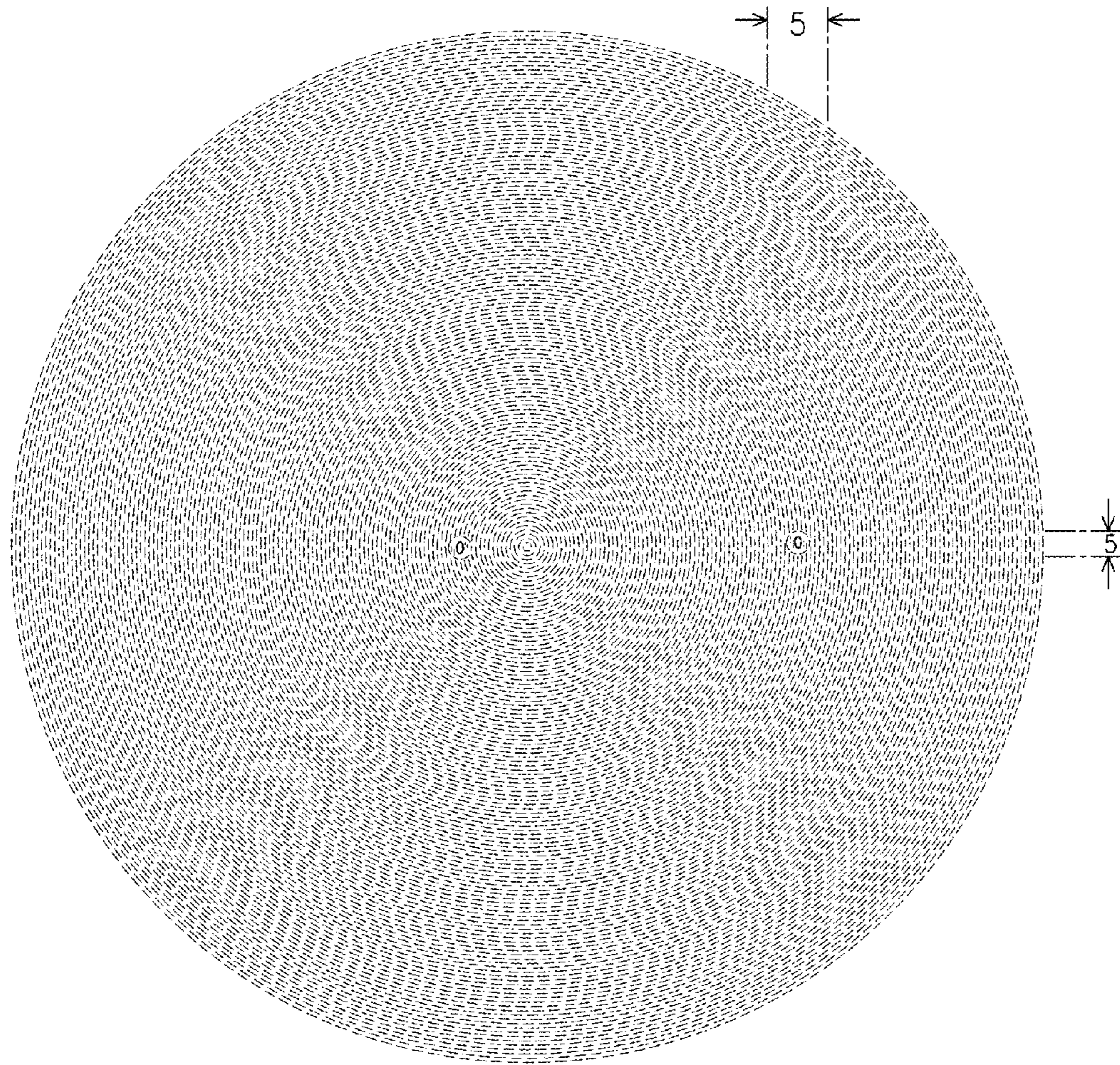


FIG. 1

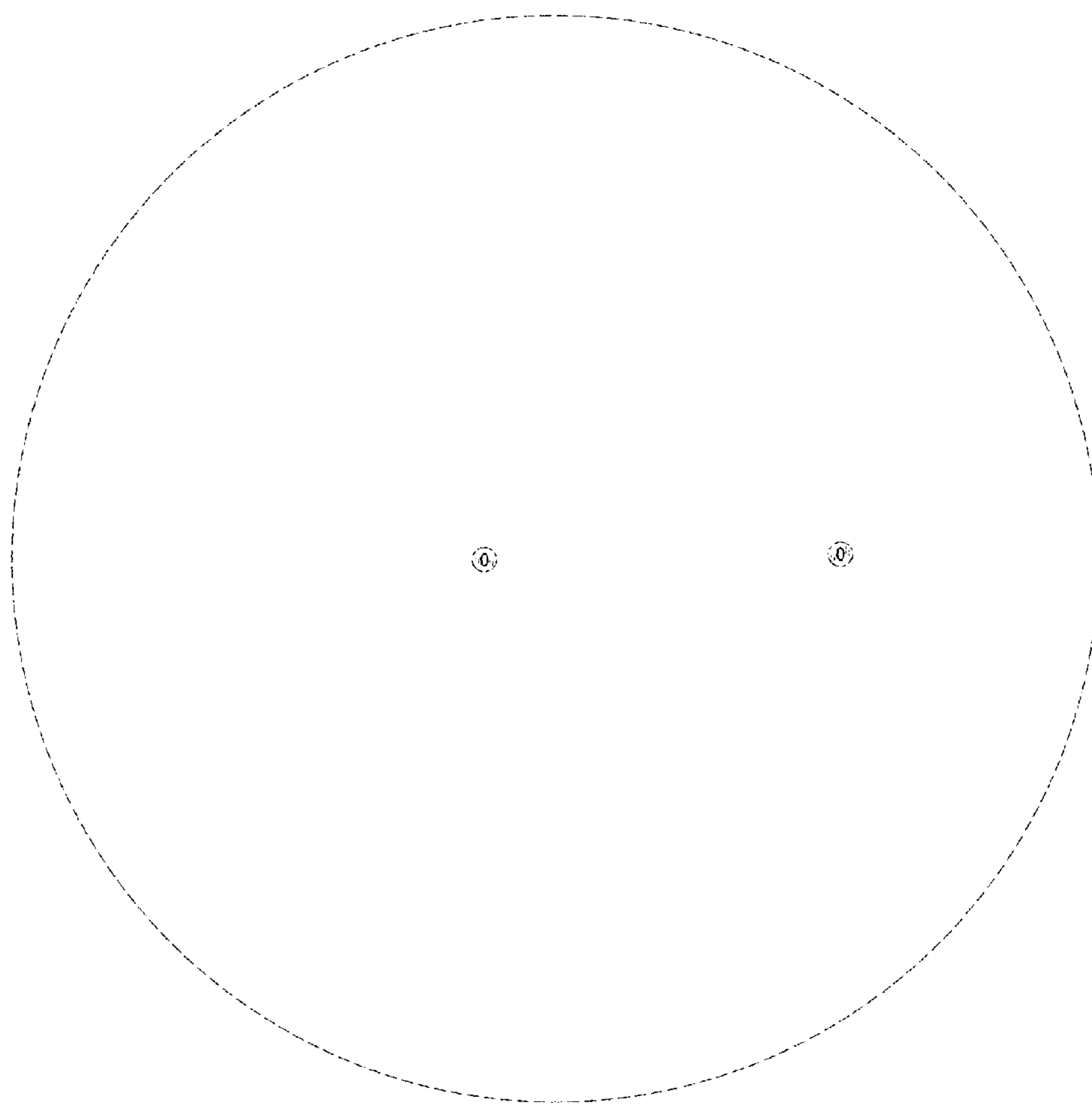


FIG. 2

FIG. 3

FIG. 4

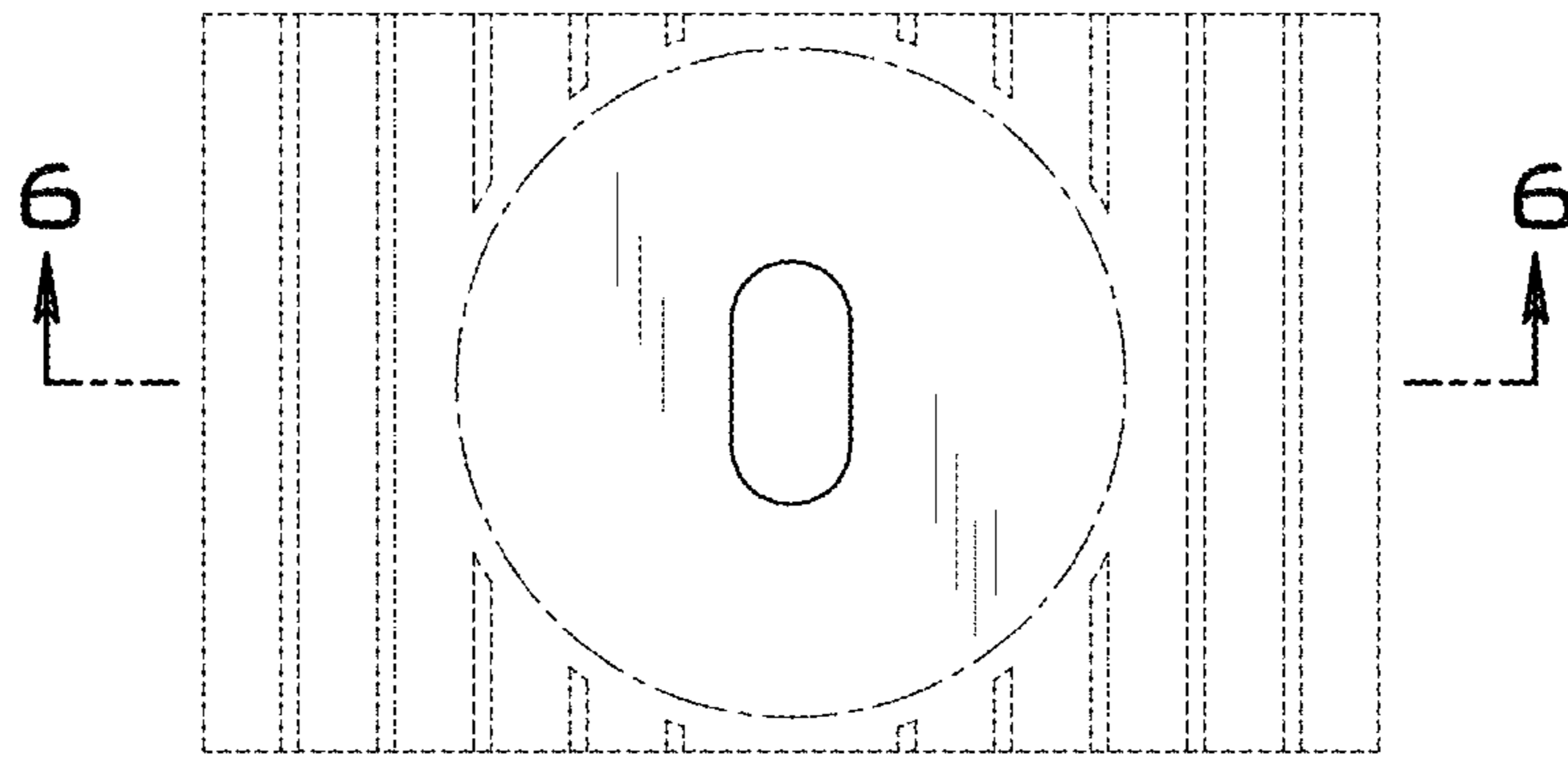


FIG. 5

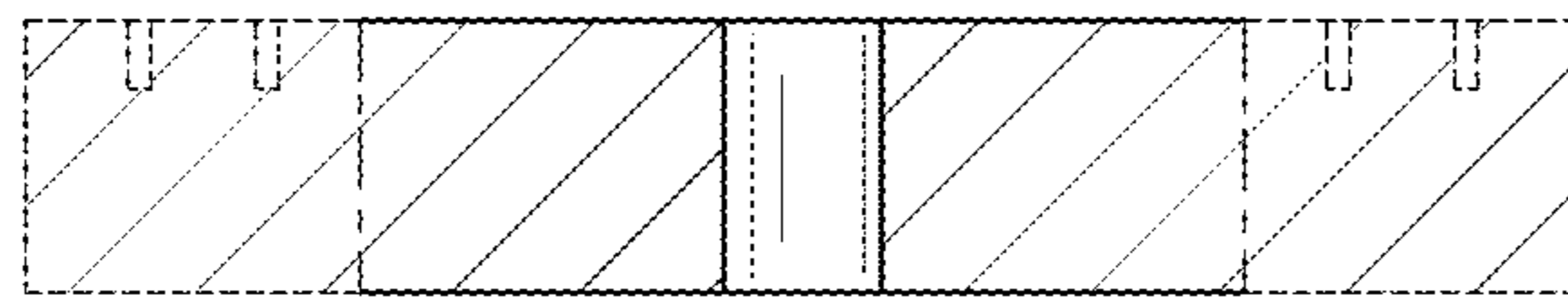


FIG. 6

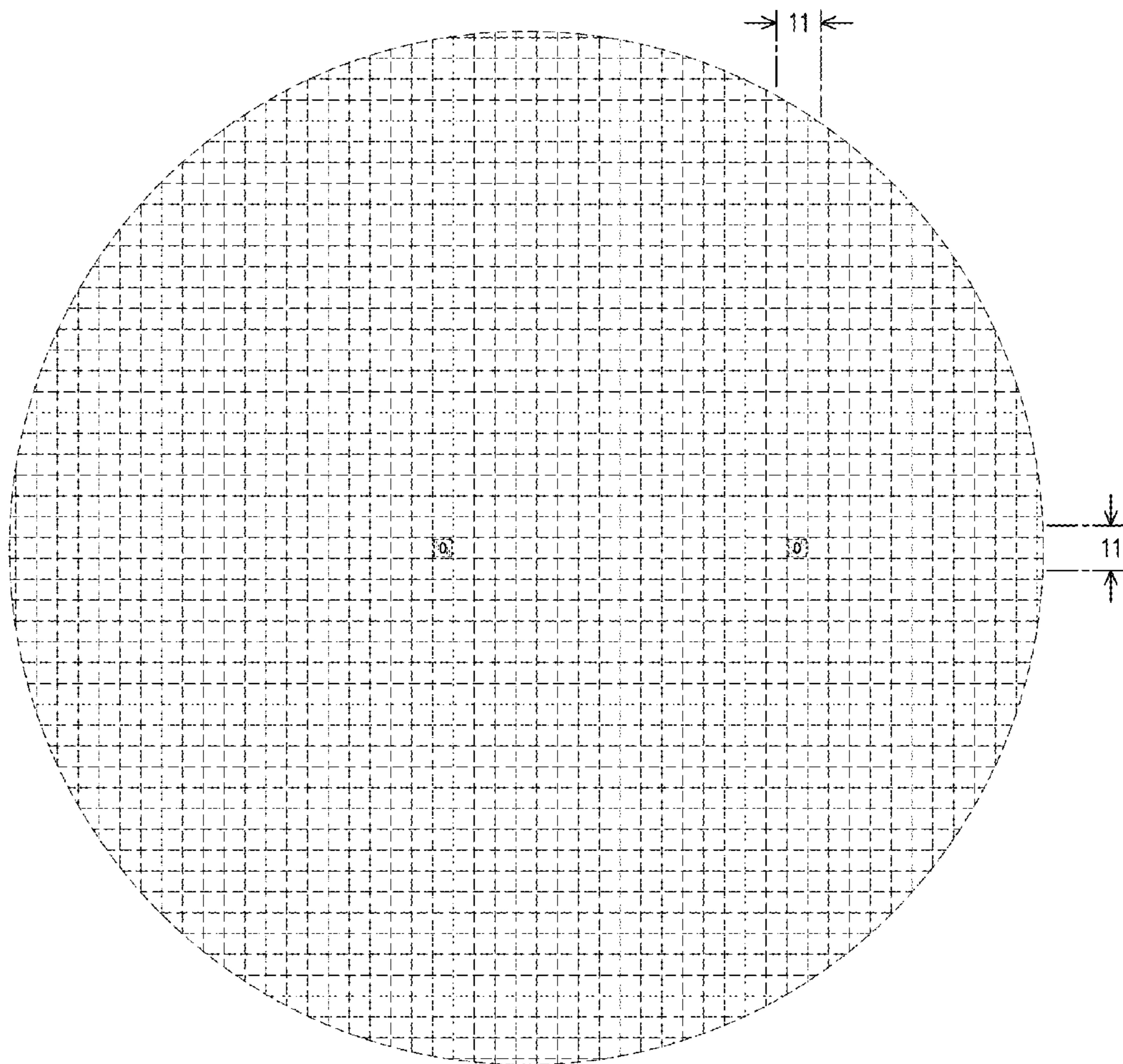


FIG. 7

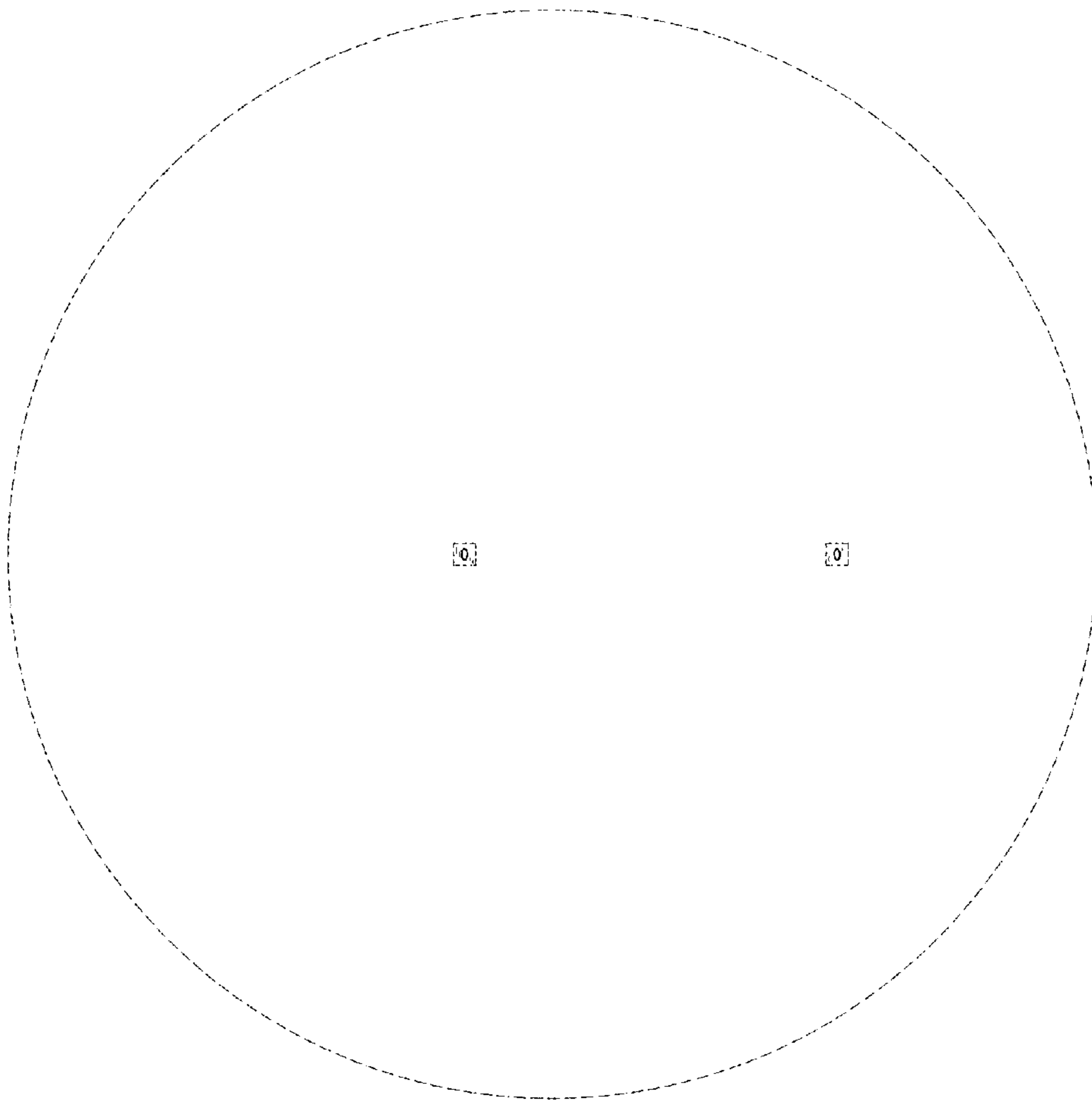


FIG. 8

FIG. 9

FIG. 10

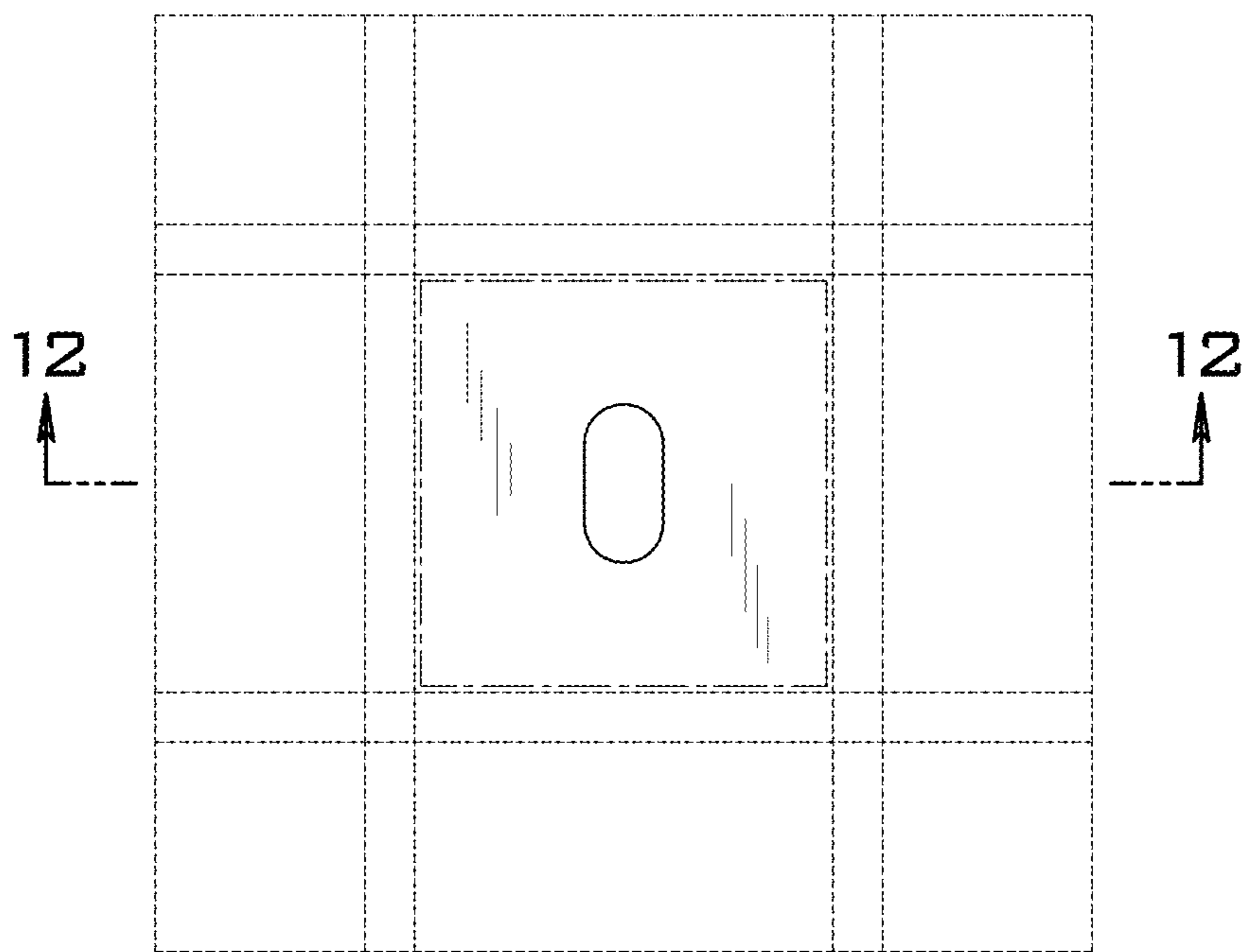


FIG. 1 1

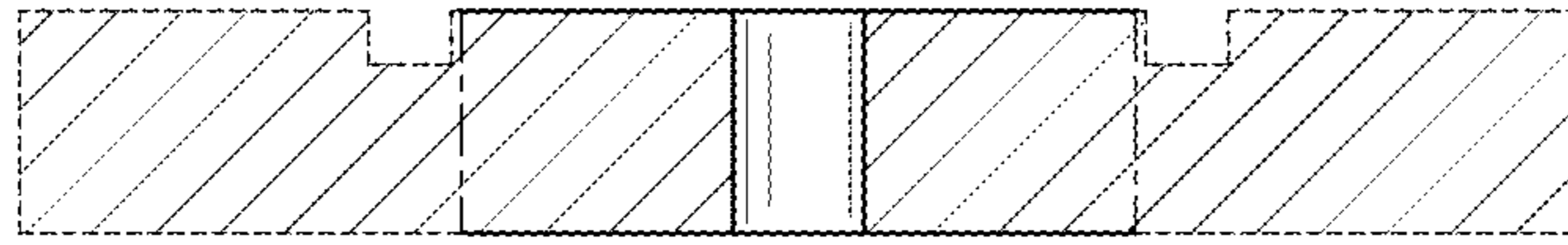


FIG. 12